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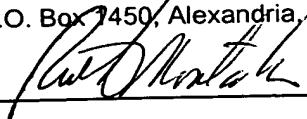
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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Attorney's Docket No.: JG-SU-5222/500577.20072

U.S. Application No.:

International Application No.: PCT/JP2004/016001

International Filing Date: OCTOBER 28, 2004

28 OCTOBER 2004

Priority Date Claimed: DECEMBER 01, 2003

01 DECEMBER 2003

Title of Invention: MANUFACTURING METHOD OF SILICON WAFER

Applicant(s) for (DO/EO/US): Sakae KOYATA and Kazushige TAKAISHI

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**PRELIMINARY AMENDMENT**

Sir:

The above-identified application is filed concurrently herewith, please amend the specification as follows:

**Amendments to the specification** begin on page 2 of this paper.

**Amendments to the Abstract** begin on page 3 of this paper.

**Remarks / Arguments** begin on page 8 of this paper.